



Docket No.: 060188-0594

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	Customer Number: 20277
Shuji HIRAO	:	Confirmation Number: 6629
Application No.: 10/624,564	:	Group Art Unit: 1753
Filed: July 23, 2003	:	Examiner: WONG, Edna
For: METHOD AND APPARATUS FOR PLATING SUBSTRATE	:	

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated May 9, 2006, having a shortened statutory period for response set to expire August 9, 2006, please amend the above identified application as follows: